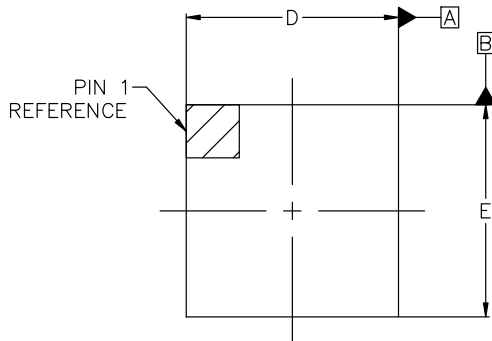
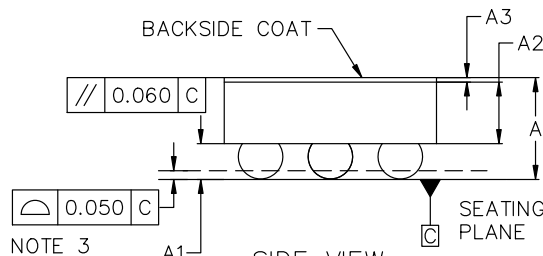


WLCSP-9 1.22x1.22x0.38, 0.40P
CASE 567QW
ISSUE C

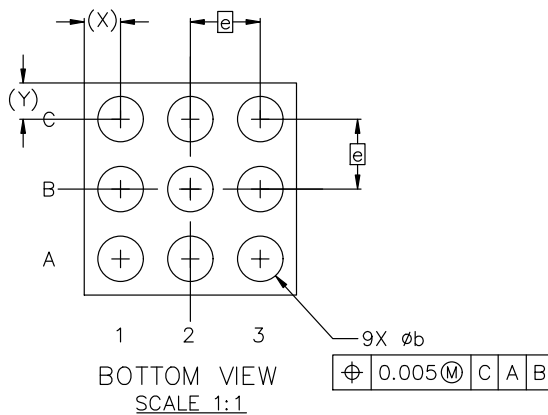
DATE 11 MAY 2026



TOP VIEW
SCALE 1:1



NOTE 3
SIDE VIEW
SCALE 1:1

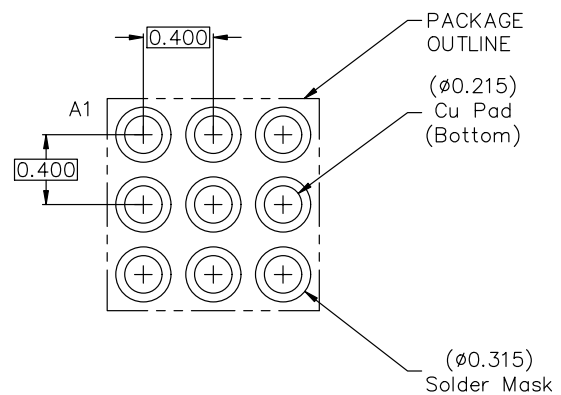


BOTTOM VIEW
SCALE 1:1

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.542	0.581	0.620
A1	0.183	0.203	0.223
A2	0.335	0.353	0.371
A3	0.022	0.025	0.027
b	0.240	0.260	0.280
D	1.185	1.215	1.245
E	1.185	1.215	1.245
e	0.400 BSC		
X	0.208 REF.		
Y	0.208 REF.		



RECOMMENDED MOUNTING FOOTPRINT

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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